

IN THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application.

1-14. (canceled)

15. (previously presented) A device, comprising:

a coolant;

a first structure including particles having an average diameter greater than about 50 μm to convert some of the coolant from liquid to vapor;

a second structure around the first structure to wet the first structure with the coolant from multiple sides; and

a plurality of outer walls to enclose the coolant, the first structure, and the second structure in an air tight manner.

16. (original) The device of claim 15, wherein the average diameter of the particles is less than about 500 μm .

17. (original) The device of claim 15, wherein the second structure has a higher thermal resistance than the first structure.

18. (original) The device of claim 15, wherein the second structure includes a wire mesh, sintered particles, fibers, or axial grooves.

19. (original) The device of claim 15, wherein a top surface of the second structure extends beyond a top surface of the first structure by an amount sufficient to ensure pooling of the coolant on the top surface of the first structure.

20. (previously presented) A system, comprising:
a heat pipe, including:
a boiling structure having a first thermal resistivity, and
a wick structure around a perimeter of the boiling structure and having a second thermal resistivity that is significantly greater than the first thermal resistivity; and
a fan to move air across at least a portion of the heat pipe.
21. (original) The system of claim 20, wherein the boiling structure includes particles having an average diameter of about 300 μm .
- 22-24. (canceled)